WHAT IS CLAIMED IS:

1. A polishing composition comprising:

silica abrasives;

a first water-soluble polymer containing a polymer compound containing a lactam ring and having a weight average molecular weight of 25,000 or more and less than 300,000;

a second water-soluble polymer containing a polymer compound containing a lactam ring and having a weight average molecular weight smaller than the weight average molecular weight of the first water-soluble polymer;

a basic compound; and

water,

wherein, the weight average molecular weight of the second water-soluble polymer is 1,000 or more and less than 25,000,

wherein, total content of the first water-soluble polymer and the second water-soluble polymer is 0.006 or less weight %, and

wherein, a ratio of a content (W1) of the first water-soluble polymer to a content (W2) of the second water soluble polymer (W1/W2) is 1/15 or more and 15/1 or less.

2. The polishing composition according to Claim 1, wherein

the first water-soluble polymer and the second water-soluble polymer are homopolymers containing a

monomer containing a compound containing a lactam ring or copolymers containing a monomer containing a compound containing a lactam ring and a monomer containing a compound not containing a lactam ring.

3. The polishing composition according to Claim 2 comprising:

as the monomer containing a compound containing a lactam ring, at least one kind selected from the group consisting of vinylpyrrolidone, vinylcaprolactam, vinylvalerolactam, vinyllaurolactam, and vinylpiperidone.

4. The polishing composition according to Claim 2 comprising:

as the homopolymer, at least one kind selected from the group consisting of polyvinylpyrrolidone, polyvinylcaprolactam, polyvinylvalerolactam, polyvinyllaurolactam, and polyvinylpiperidone.

5. The polishing composition according to Claim 1, wherein

the first water-soluble polymer and the second water-soluble polymer are polyvinylpyrrolidones.

6. The polishing composition according to any one of Claims 1 to 5, wherein

a total content of the first water-soluble polymer and the second water-soluble polymer is 0.05 mass% or less.

~~7. The polishing composition according to any one of Claims 1 to 6, wherein~~

~~a ratio of a content (W1) of the first water-soluble polymer to a content (W2) of the second water-soluble polymer (W1/W2) is 1/15 or more and 15/1 or less.~~

~~8~~7. The polishing composition according to any one of Claims 1 to ~~7~~ 6 further comprising:

an erosion inhibitor containing a surfactant or a compound having a guanidino group.

~~9~~8. The polishing composition according to Claim ~~8~~7, wherein

the erosion inhibitor contains a surfactant and the surfactant is an anionic surfactant.

~~10~~9. The polishing composition according to Claim ~~8~~7, wherein

the erosion inhibitor contains a compound having a guanidino group and the compound having a guanidino group is creatinine or arginine.

~~11~~10. A polishing method comprising:

polishing a polishing object containing a film containing a silicon material having a silicon-silicon bond using the polishing composition according to any one of Claims 1 to ~~10~~9.

~~12~~11. A polishing method comprising:

polishing a polishing object having a film containing a silicon material having a silicon-silicon bond formed on a pattern containing an insulating film using the polishing composition according to any one of Claims 1 to ~~10~~ 9 by a CMP method to form a circuit pattern containing the silicon material.